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## **Inventor Name Search Result**

Your Search was:

Last Name = HEDLER First Name = HARRY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08450959	Not Issued	161	05/23/1995	THERMOELECTRIC RECEIVER COMPONENT FOR INFRARED AND VISIBLE RADIATION WITH HIGH DIRECTIVITY AND SELECTIVITY	HEDLER, HARRY
09509228	Not Issued	161	09/13/2000	Method for producing a multilevel carrier (substrate), especially for multichip modules	HEDLER, HARRY
09658713	6406937	150	09/11/2000	METHOD FOR PRODUCING AN ELECTRICAL CONNECTION BETWEEN THE FRONT AND REAR SIDES OF SEMICONDUCTOR CHIPS	HEDLER, HARRY
<u>09806401</u>	Not Issued	161	10/22/2001	Electronic module, especially a multichip module, with multi-layer metallization and corresponding production method	HEDLER, HARRY
<u>09944796</u>	<u>6664176</u>	150	08/31/2001	PAD- REROUTING FOR INTEGRATED CIRCUIT CHIPS	HEDLER, HARRY
10022226	Not Issued	94	12/17/2001	ELECTRONIC COMPONENT WITH FLEXIBLE BONDING PADS AND METHOD OF PRODUCING SUCH A COMPONENT	HEDLER, HARRY
10022606	6555415	150	12/17/2001	ELECTRONIC CONFIGURATION WITH FLEXIBLE BONDING PADS	HEDLER, HARRY
10032941	<u>6888256</u>	150		COMPLIANT RELIEF WAFER LEVEL PACKAGING	HEDLER, HARRY
10044000	6727576	150		TRANSFER WAFER LEVEL PACKAGING	HEDLER, HARRY
10044136	6638870	150	01/10/2002	FORMING A STRUCTURE ON A WAFER	HEDLER, HARRY

10051543	Not Issued	160	01/22/2002	Transfer wafer level packaging	HEDLER, HARRY
10056356	6858799	150	01/24/2002	ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
10105467	6852931	150	03/26/2002	CONFIGURATION HAVING AN ELECTRONIC DEVICE ELECTRICALLY CONNECTED TO A PRINTED CIRCUIT BOARD	HEDLER, HARRY
10132826	Not Issued	41	04/25/2002	Electronic component with semiconductor chips, electronic assembly composed of stacked semiconductor chips, and methods for producing an electronic component and an electronic assembly	HEDLER, HARRY
10135273	6861291	150	04/30/2002	METHOD PRODUCING A CONTACT CONNECTION BETWEEN A SEMICONDUCTOR CHIP AND A SUBSTRATE AND THE CONTACT CONNECTION	HEDLER, HARRY
10155337	6756540	150	05/24/2002	SELF-ADHERING CHIP	HEDLER, HARRY
10157175	6826037	150	05/29/2002	ELECTRONIC STRUCTURE	HEDLER, HARRY
10159848	6744127	150	05/31/2002	SEMICONDUCTOR CHIP, MEMORY MODULE AND METHOD FOR TESTING THE SEMICONDUCTOR CHIP	HEDLER, HARRY
10179751	6630723	150	06/25/2002	LASER PROGRAMMING OF INTEGRATED CIRCUITS	HEDLER, HARRY
10195958	6864575	150	07/16/2002	ELECTRONIC INTERFACE STRUCTURES AND METHODS	HEDLER, HARRY
10205081	6851598	150	07/25/2002	ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP AND METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
10236895	6807064	150	·	ELECTRONIC COMPONENT WITH AT LEAST ONE SEMICONDUCTOR CHIP AND	HEDLER, HARRY

				METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	
10252449	6936928	150	09/23/2002	SEMICONDUCTOR COMPONENT AND METHOD FOR ITS PRODUCTION	HEDLER, HARRY
10260872	6897568	150	09/30/2002	ELECTRONIC COMPONENT WITH FLEXIBLE CONTACTING PADS AND METHOD FOR PRODUCING THE ELECTRONIC COMPONENT	HEDLER, HARRY
<u>10284649</u>	6919232	150	10/31/2002	PROCESS FOR PRODUCING A SEMICONDUCTOR CHIP	HEDLER, HARRY
10285924	6714418	150	11/01/2002	METHOD FOR PRODUCING AN ELECTRONIC COMPONENT HAVING A PLURALITY OF CHIPS THAT ARE STACKED ONE ABOVE THE OTHER AND CONTACT- CONNECTED TO ONE ANOTHER	HEDLER, HARRY
10298772	Not Issued	41	11/18/2002	Process for producing a component module	HEDLER, HARRY
10298837	6845554	150	11/18/2002	METHOD FOR CONNECTION OF CIRCUIT UNITS	HEDLER, HARRY
10336373	Not Issued	71	01/03/2003	Method of producing semiconductor chips with a chip edge guard, in particular for wafer level packaging chips	HEDLER, HARRY
10440480	6897088	150		METHOD FOR CONNECTING CIRCUIT DEVICES	HEDLER, HARRY
<u>10446396</u>	Not Issued	93	05/28/2003	CONNECTION OF INTEGRATED CIRCUITS	HEDLER, HARRY
<u>10464429</u>	6916185	150	06/18/2003	CONNECTION OF INTEGRATED CIRCUIT TO A SUBSTRATE	HEDLER, HARRY
10477967	Not Issued	20	05/10/2004	Method for producing an electronic component, especially a memory chip	HEDLER, HARRY
10625495	6887777	150		AN INTEGRATED CIRCUIT TO A SUBSTRATE AND CORRESPONDING CIRCUIT ARRANGEMENT	HEDLER, HARRY
<u>10630632</u>	Not	95	07/29/2003	SEMICONDUCTOR CIRCUIT	HEDLER, HARRY

	Issued			MODULE AND METHOD FOR FABRICATING SEMICONDUCTOR CIRCUIT MODULES	
10634242	6905954	150	08/05/2003	METHOD FOR PRODUCING A SEMICONDUCTOR DEVICE AND CORRESPONDING SEMICONDUCTOR DEVICE	HEDLER, HARRY
10637899	6927157	150	08/08/2003	INTEGRATED CIRCUIT AND METHOD FOR PRODUCING A COMPOSITE COMPRISING A TESTED INTEGRATED CIRCUIT AND AN ELECTRICAL DEVICE	HEDLER, HARRY
10642063	Not Issued	95	08/15/2003	METHOD OF PRODUCING A SEMICONDUCTOR COMPONENT HAVING A COMPLIANT BUFFER LAYER	HEDLER, HARRY
10642092	Not Issued	71	08/15/2003	Method for fabricating connection regions of an integrated circuit, and integrated circuit having connection regions	HEDLER, HARRY
10721745	Not Issued	41	11/26/2003	Method for producing an integrated circuit with a rewiring device and corresponding integrated circuit	HEDLER, HARRY
10721787	Not Issued	71	11/26/2003	Semiconductor component and method for producing same	HEDLER, HARRY
10747670	Not Issued	71		Method for connecting an integrated circuit to a substrate and corresponding arrangement	HEDLER, HARRY
10754172	Not Issued	71	01/09/2004	CARRIER FOR RECEIVING AND ELECTRICALLY CONTACTING INDIVIDUALLY SEPARATED DIES	HEDLER, HARRY
10790907	Not Issued	30	03/02/2004	Integrated circuit with re-route layer and stacked die assembly	HEDLER, HARRY
10836143	Not Issued	30	04/30/2004	Semiconductor device and method for fabricating the semiconductor device	HEDLER, HARRY
10855891	Not Issued	41	05/28/2004	Contact-connection device for electronic circuit units and production method	HEDLER, HARRY
10900578	Not Issued	30	07/28/2004	Semiconductor module and method for producing a semiconductor module	HEDLER, HARRY

10952383	Not Issued	30	Method for producing a multichip module and multichip module	HEDLER, HARRY
10963434	Not Issued	30	Electronic component with flexible contacting pads and method for producing the electronic component	HEDLER, HARRY
11008081	Not Issued	30	Configuration having an electronic device electrically connected to a printed circuit board	HEDLER, HARRY

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Application#	Patent#	Status	Date Filed	Title	Inventor Name	
11030799	Not Issued	30	01/07/2005	Method of producing an electronic component	HEDLER, HARRY	
11038465	Not Issued	30	01/21/2005	Semiconductor device	HEDLER, HARRY	
11061762	Not Issued	19		Semiconductor component having a CSP housing	HEDLER, HARRY	
11086922	Not Issued	30		Integrated device and electronic system	HEDLER, HARRY	
11098780	Not Issued	30	04/04/2005	Stacked die package	HEDLER, HARRY	
11124515	Not Issued	30	05/06/2005	Method of producing an electronic component with flexible bonding pads	HEDLER, HARRY	
11126392	Not Issued	30	05/11/2005	Method of manufacturing a semiconductor device comprising stacked chips and a corresponding semiconductor device	HEDLER, HARRY	
11137061	Not Issued	20	05/25/2005	Flexible contact-connection device	HEDLER, HARRY	
11140687	Not Issued	30	05/31/2005	Manufacturing method for an electronic component assembly and corresponding electronic component assembly	HEDLER, HARRY	
11153510	Not Issued	20	06/15/2005	Method for connecting an integrated circuit to a substrate and corresponding circuit arrangement	HEDLER, HARRY	
11172083	Not Issued	20		Semiconductor device with semiconductor components connected to one another	HEDLER, HARRY	
<u>11185472</u>	Not Issued	19		Method for connection of an integrated circuit to a substrate, and a corresponding circuit	HEDLER, HARRY	

I				arrangement	
	11195462	Not Issued	19	Method of manufacturing a semiconductor structure having a wafer through-contact and a corresponding semiconductor structure	HEDLER, HARRY

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### **Inventor Name Search Result**

Your Search was:

Last Name = MUFF First Name = SIMON

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Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>09154484</u>	6104615	150	09/16/1998	SEMICONDUCTOR COMPONENT ASSEMBLY	MUFF, SIMON
09401386	Not Issued	164	09/22/1999	SEMICONDUCTOR COMPONENT HAVING A THERMALLY CONDUCTIVE PLATE	MUFF, SIMON
<u>09514265</u>	6534345	150	02/28/2000	METHOD FOR MOUNTING A SEMICONDUCTOR CHIP ON A CARRIER LAYER AND DEVICE FOR CARRYING OUT THE METHOD	MUFF, SIMON
09771912	6798045	150	01/29/2001	LEAD FRAME, CIRCUIT BOARD WITH LEAD FRAME, AND METHOD FOR PRODUCING THE LEAD FRAME	MUFF, SIMON
<u>09776951</u>	Not Issued	92	02/05/2001	METHOD AND DEVICE FOR ADAPTING/TUNING SIGNAL TRANSIT TIMES ON LINE SYSTEMS OR NETWORKS BETWEEN INTEGRATED CIRCUITS	MUFF, SIMON
09793344	6434035	150	02/26/2001	MEMORY SYSTEM	MUFF, SIMON
10010164	Not Issued	161	11/13/2001	IC chip	MUFF, SIMON
10137511	<u>6911732</u>			INTEGRATED CIRCUIT	MUFF, SIMON
10145579	6686764	150	05/14/2002	APPARATUS AND METHOD FOR REDUCING REFLEXIONS IN A MEMORY BUS SYSTEM	MUFF, SIMON
10149892	Not Issued	30	10/01/2004	Encasing arrangement for a semicoductor component	MUFF, SIMON
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10152496	Not Issued	161	05/21/2002	Circuit board for memory components	MUFF, SIMON
10155847	Not Issued	161	05/24/2002	Arrangement of memory chip housings on a DIMM circuit board	MUFF, SIMON
10266322	6765302	150	10/08/2002	SEMICONDUCTOR MODULE HAVING A CONFIGURABLE DATA WIDTH OF AN OUTPUT BUS, AND A HOUSING CONFIGURATION HAVING A SEMICONDUCTOR MODULE	MUFF, SIMON
10345057	6783372	150	01/15/2003	APPARATUS FOR CONNECTING SEMICONDUCTOR MODULES	MUFF, SIMON
10675492	Not Issued	93	09/30/2003	METHOD FOR CALIBRATING SEMICONDUCTOR DEVICES USING A COMMON CALIBRATION REFERENCE AND A CALIBRATION CIRCUIT	MUFF, SIMON
10721787	Not Issued	71	11/26/2003	Semiconductor component and method for producing same	MUFF, SIMON
10772356	6894525	150	02/06/2004	METHOD AND DEVICE FOR TIME MEASUREMENT ON SEMICONDUCTOR MODULES EMPLOYING THE BALL-GRID- ARRAY TECHNIQUE	MUFF, SIMON
10797941	Not Issued	20	03/11/2004	Topology for providing clock signals to multiple circuit units on a circuit module	MUFF, SIMON
11126408	Not Issued	30		Stacked semiconductor memory device	MUFF, SIMON
<u>11172083</u>	Not Issued	20	06/30/2005	Semiconductor device with semiconductor components connected to one another	MUFF, SIMON
11192335	Not Issued	19	07/29/2005	Semiconductor memory module and system	MUFF, SIMON

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